# International Rectifier

# ST303C..C SERIES

#### **INVERTER GRADE THYRISTORS**

#### **Puk Version**

620A

#### **Features**

- Metal case with ceramic insulator
- International standard case TO-200AB (E-PUK)
- All diffused design
- Center amplifying gate
- Guaranteed high dV/dt
- Guaranteed high dl/dt
- High surge current capability
- Low thermal impedance
- High speed performance

#### **Typical Applications**

- Inverters
- Choppers
- Induction heating
- All types of force-commutated converters

case style TO-200AB (E-PUK)

### Major Ratings and Characteristics

Parameters		ST303CC	Units	
I <sub>T(AV)</sub>		620	А	
	@ T <sub>hs</sub>	55	°C	
I <sub>T(RMS)</sub>		1180	А	
	@ T <sub>hs</sub>	25	°C	
I <sub>TSM</sub>	@ 50Hz	7950	А	
	@ 60Hz	8320	А	
I <sup>2</sup> t	@ 50Hz	316	KA <sup>2</sup> s	
	@ 60Hz	289	KA <sup>2</sup> s	
V <sub>DRM</sub> /V <sub>RRM</sub>		400 to 1200	V	
t <sub>q</sub> range (*)		10 to 30	μs	
T <sub>J</sub>		- 40 to 125	°C	

<sup>(\*)</sup>  $t_q = 10$  to 20µs for 400 to 800V devices  $t_q = 15$  to 30µs for 1000 to 1200V devices

### **ELECTRICAL SPECIFICATIONS**

#### Voltage Ratings

Type number	Voltage Code	V <sub>DRM</sub> /V <sub>RRM</sub> , maximum repetitive peak voltage	V <sub>RSM</sub> , maximum non-repetitive peak voltage	$I_{DRM}/I_{RRM}$ max. @ $T_J = T_J$ max.
		V	V	mA
	04	400	500	
ST303CC	08	800	900	50
0100000	10	1000	1100	30
	12	1200	1300	

#### **Current Carrying Capability**

Current Garrying Capability									
Frequency	180∘el	I <sub>TM</sub>	180°6	I <sub>TM</sub>	100μ	S I <sub>TM</sub>	Units		
50Hz	1314	1130	2070	1940	6930	6270			
400Hz	1260	1040	2190	1880	3440	2960			
1000Hz	900	700	1900	1590	1850	1540	Α		
2500Hz	340	230	910	710	740	560			
Recovery voltage Vr	50	50	50	50	50	50	.,		
Voltage before turn-on Vd	V <sub>D</sub>	RM	V	DRM	V <sub>DRM</sub>		· v		
Rise of on-state current di/dt	50	50	-	-	-	-	A/μs		
Heatsink temperature	40	55	40	55	40	55	°C		
Equivalent values for RC circuit	10Ω/0	.47µF	10Ω/0	.47µF	10Ω/0	.47µF			

#### On-state Conduction

	Parameter	ST303CC	Units	Conditions					
I <sub>T(AV)</sub> Max. average on-state current		620 (230)	Α	180° conduction, half sine wave					
. ,	@ Heatsink temperature	55 (85)	°C	double side	double side (single side) cooled				
I <sub>T(RMS)</sub>	Max. RMS on-state current	1180		DC @ 25°C	25°C heatsink temperature double side				
I <sub>TSM</sub>	Max. peak, one half cycle,	7950		t = 10ms	No voltage				
	non-repetitive surge current	8320	Α	t = 8.3ms	reapplied				
		6690		t = 10ms	100% V <sub>RRM</sub>				
		7000		t = 8.3ms	reapplied	Sinusoidal half wave,			
I <sup>2</sup> t	Maximum I2t for fusing	316		t = 10ms	No voltage	Initial $T_J = T_J \text{ max}$			
		289	1642	t = 8.3ms	reapplied				
		224	KA <sup>2</sup> s	t = 10ms	100% V <sub>RRM</sub>				
		204		t = 8.3ms	reapplied				
I²√t	Maximum I <sup>2</sup> √t for fusing	3160	KA²√s	t = 0.1 to 10ms, no voltage reapplied					

#### On-state Conduction

	Parameter	ST303CC	Units	Conditions
V <sub>TM</sub>	Max. peak on-state voltage	2.16		$I_{TM}$ = 1255A, $T_J = T_J$ max, $t_p$ = 10ms sine wave pulse
	Low level value of threshold voltage	1.44	V	$(16.7\% \text{ x } \pi \text{ x }  _{T(AV)} < I < \pi \text{ x }  _{T(AV)}), T_J = T_J \text{ max.}$
V <sub>T(TO)2</sub>	High level value of threshold voltage	1.48		$(I > \pi \times I_{T(AV)}), T_J = T_J \text{ max.}$
r <sub>t1</sub>	Low level value of forward slope resistance	0.57	mΩ	$(16.7\% \times \pi \times I_{T(AV)} < I < \pi \times I_{T(AV)}), T_J = T_J \text{ max.}$
r <sub>t2</sub>	High level value of forward slope resistance	0.56	11122	$(I > \pi \times I_{T(AV)}), T_J = T_J \text{ max.}$
I <sub>H</sub>	Maximum holding current	600	mA	$T_J = 25^{\circ}C, I_T > 30A$
I <sub>L</sub>	Typical latching current	1000	IIIA	$T_J = 25^{\circ}C, V_A = 12V, Ra = 6\Omega, I_G = 1A$

### Switching

	Parameter	ST303	3CC	Units	Conditions
di/dt	Max. non-repetitive rate of rise of turned-on current	1000		A/µs	$I_{J} = I_{J} \text{ max}, V_{DRM} = \text{rated } V_{DRM}$ $I_{TM} = 2 \text{ x di/dt}$
t <sub>d</sub>	Typical delay time	0.83		μs	$T_J$ = 25°C, $V_{DM}$ = rated $V_{DRM}$ , $I_{TM}$ = 50A DC, $t_p$ = 1 $\mu$ s Resistive load, Gate pulse: 10V, 5 $\Omega$ source
		Min	Max	μδ	$T_J = T_J \text{ max}, I_{TM} = 550\text{A}, \text{ commutating di/dt} = 40\text{A/µs}$
t <sub>q</sub>	Max. turn-off time (*)	10	30		$V_R = 50V$ , $t_p = 500\mu s$ , dv/dt: see table in device code

<sup>(\*)</sup>  $t_q = 10$  to 20µs for 400 to 800V devices;  $t_q = 15$  to 30µs for 1000 to 1200V devices.

### Blocking

	Parameter	ST303CC	Units	Conditions
dv/dt	Maximum critical rate of rise of off-state voltage	500	V/μs	$T_J = T_J$ max. linear to 80% $V_{DRM}$ , higher value available on request
I <sub>RRM</sub> I <sub>DRM</sub>	Max. peak reverse and off-state leakage current	50	mA	$T_J = T_J \text{ max, rated V}_{DRM}/V_{RRM} \text{ applied}$

### Triggering

	Parameter	ST303CC	Units	Conditions
P <sub>GM</sub>	Maximum peak gate power	60	147	T T may 6 5011- 40/ 50
P <sub>G(AV)</sub>	Maximum average gate power	10	W	$T_J = T_J \text{ max, } f = 50 \text{Hz, } d\% = 50$
I <sub>GM</sub>	Max. peak positive gate current	10	Α	$T_J = T_J \text{ max, } t_p \le 5 \text{ms}$
+V <sub>GM</sub>	Maximum peak positive gate voltage	20	v	T - T may t < 5mg
-V <sub>GM</sub>	Maximum peak negative gate voltage	5	V	$T_J = T_J \text{ max, } t_p \le 5 \text{ms}$
I <sub>GT</sub>	Max. DC gate current required to trigger	200	mA	T 25°C V 12V Pa 60
V <sub>GT</sub>	Max. DC gate voltage required to trigger	3	V	$T_J = 25^{\circ}C$ , $V_A = 12V$ , $Ra = 6\Omega$
I <sub>GD</sub>	Max. DC gate current not to trigger	20	mA	T. T. many rested V. applied
V <sub>GD</sub>	Max. DC gate voltage not to trigger	0.25	٧	$T_J = T_J$ max, rated $V_{DRM}$ applied

#### Thermal and Mechanical Specification

	<u> </u>			
	Parameter	ST303CC	Units	Conditions
T <sub>J</sub>	Max. operating temperature range	-40 to 125	°C	
T <sub>stg</sub>	Max. storage temperature range	-40 to 150		
R <sub>thJ-h</sub>	Max. thermal resistance,	0.09	16/104	DC operation single side cooled
	junction to heatsink	0.04	K/W	DC operation double side cooled
R <sub>thC-h</sub>	s Max. thermal resistance,	0.020	K/W	DC operation single side cooled
	case to heatsink	0.010	10,44	DC operation double side cooled
F	Mounting force, ± 10%	9800	N	
		(1000)	(Kg)	
wt	Approximate weight	83	g	
	Case style	TO - 200AB (E-PUK)		See Outline Table

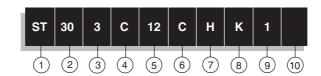
## $\Delta R_{\text{thJ-hs}} \, \text{Conduction}$

(The following table shows the increment of thermal resistence R<sub>In.I-hs</sub> when devices operate at different conduction angles than DC)

	פודעונו									
Conduction angle	Sinusoidal	conduction	Rectangula	r conduction	Units	Conditions				
	Conduction angle	Single Side	Double Side	Single Side			Conditions			
	180°	0.010	0.010	0.007	0.007					
	120°	0.012	0.012	0.012	0.013					
	90°	0.015	0.015	0.016	0.017	K/W	$T_J = T_J \text{ max.}$			
	60°	0.022	0.022	0.023	0.023					
	30°	0.036	0.036	0.036	0.037					

#### Ordering Information Table

#### **Device Code**



- 1 Thyristor
- 2 Essential part number
- 3 3 = Fast turn off
- 4 C = Ceramic Puk
- 5 Voltage code: Code x 100 = V<sub>RRM</sub> (See Voltage Rating Table)
- 6 C = Puk Case TO-200AB (E-PUK)
- 7 Reapplied dv/dt code (for t<sub>a</sub> test condition)
- 8 t<sub>a</sub> code -
- 9 0 = Eyelet term. (Gate and Aux. Cathode Unsoldered Leads)
  - 1 = Fast-on term. (Gate and Aux. Cathode Unsoldered Leads)
  - 2 = Eyelet term. (Gate and Aux. Cathode Soldered Leads)
  - 3 = Fast-on term. (Gate and Aux. Cathode Soldered Leads)
- 10 Critical dv/dt:

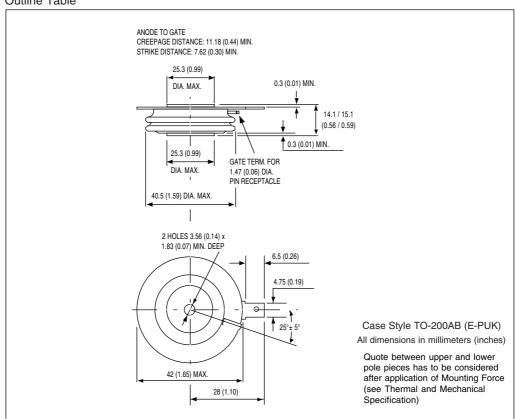
None = 500V/µsec (Standard value)

L = 1000V/µsec (Special selection)

dv/dt - t <sub>q</sub> combinations available									
dv/dt	(V/µs)	20	50	100	200	400			
t <sub>q</sub> (µs)	10	CN	DN	EN	FN *	ZH			
-	12	CM	DM	EM	FM	HM			
up to 800V	15	CL	DL	EL	FL *	HL			
	20	CK	DK	EK	FK *	HK			
t <sub>q</sub> (µs)	15	CL							
ч	18	CP	DP						
	20	CK	DK	EK	FK *	HK			
only for	25	CJ	DJ	EJ	FJ *	HJ			
1000/1200V	30		DH	EH	FH	НН			

\*Standard part number.
All other types available only on request.

#### Outline Table



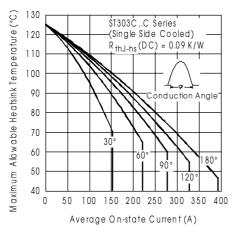


Fig. 1 - Current Ratings Characteristics

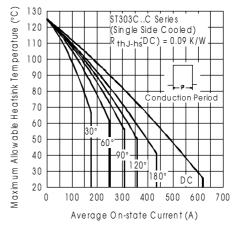


Fig. 2 - Current Ratings Characteristics

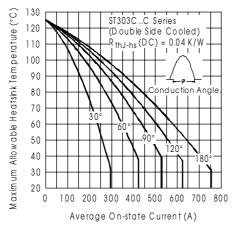


Fig. 3 - Current Ratings Characteristics

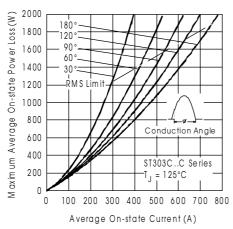


Fig. 5 - On-state Power Loss Characteristics

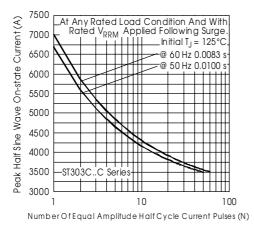


Fig. 7 - Maximum Non-repetitive Surge Current Single and Double Side Cooled

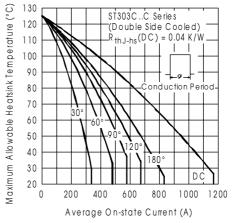


Fig. 4 - Current Ratings Characteristics

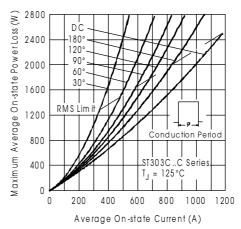


Fig. 6 - On-state Power Loss Characteristics

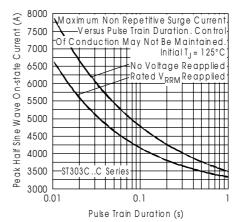


Fig. 8 - Maximum Non-repetitive Surge Current Single and Double Side Cooled

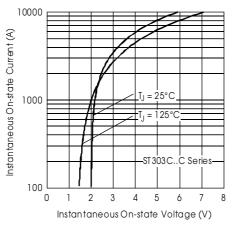


Fig. 9 - On-state Voltage Drop Characteristics

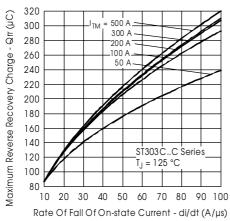


Fig. 11 - Reverse Recovered Charge Characteristics

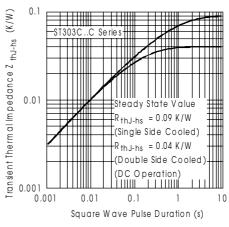


Fig. 10 - Thermal Impedance  $Z_{thJ\text{-}hs}$  Characteristics

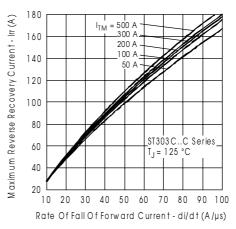


Fig. 12 - Reverse Recovery Current Characteristics

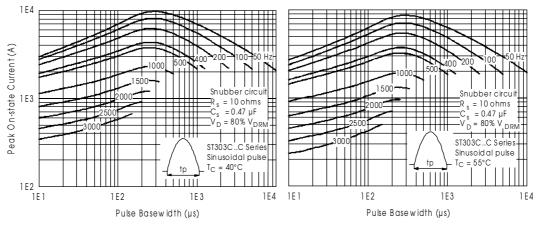


Fig. 13 - Frequency Characteristics

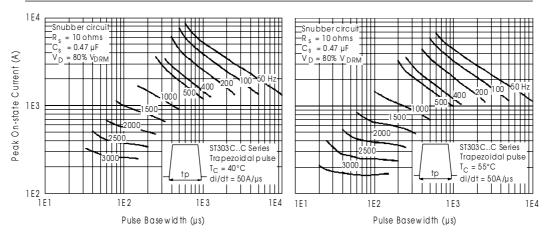


Fig. 14 - Frequency Characteristics

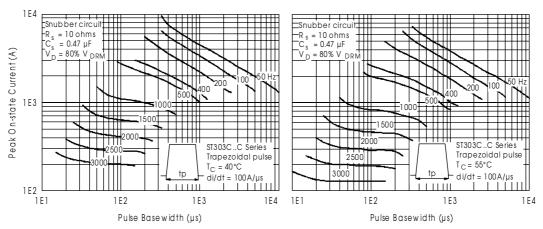


Fig. 15 - Frequency Characteristics

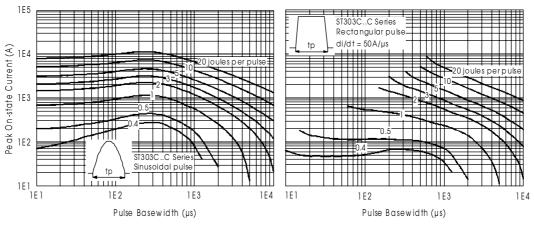


Fig. 16 - Maximum On-state Energy Power Loss Characteristics

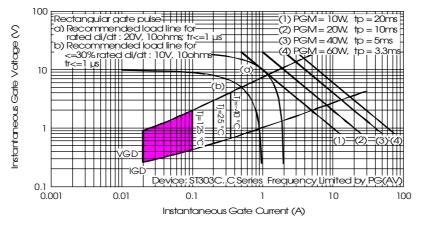


Fig. 17 - Gate Characteristics